

Product / Process Change Notification



N° 2016-069-A

Dear Customer,

Please find attached our INFINEON Technologies PCN:

Change of assembly to Amkor Philippines and bill of material (incl. Cu wirebond) and additionally change of wafer production and wafer test to Kulim for TLE7269G

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before **09. March 2017**.
- Infineon aligns with the widely-recognized JEDEC STANDARD “**JESD46**“, which stipulates: **“Lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change.”**

Your prompt reply will help Infineon Technologies to assure a smooth and well executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your attention and response to this matter is greatly appreciated.

Disclaimer:

If we do not receive any response by the date in the PCN above we consider this as the acceptance of the PCN. After the last order date as stated herein, purchase orders related to the unchanged product(s) cannot be accepted.

Infineon Technologies AG
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Chairman of the Supervisory Board: Wolfgang Mayrhuber
Management Board: Dr. Reinhard Ploss (CEO), Dominik Asam, Dr. Helmut Gassel, Jochen Hanebeck
Registered Office: Neubiberg Commercial Register
Amtsgericht München HRB 126492

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► **Products affected:**

Sales Name	SP N°	OPN	Package
TLE7269G	SP000104277	TLE7269GXUMA1	PG-DSO-14

► **Detailed Change Information:**

Subject: Change of wafer production and wafer test to Kulim and assembly location from PT Unisem Batam Island, Indonesia to Amkor Philippines and implementation of AMKOR's standard automotive Bill of Material (BoM) affecting TLE7269G.

Reason: According to the global Infineon production strategy, the wafer production and wafer test of TLE7269G will be transferred to Kulim, Malaysia and the assembly of TLE7269G will be transferred to Amkor Technologies, Philippines.
Amkor Philippines, using state-of-the-art bill of material (BoM), has a long term experience as automotive assembly subcontractor for Infineon and is TS16949 certified and Infineon robust and green qualified.

Description:

	<u>Old</u>	<u>New</u>
Wafer production	<ul style="list-style-type: none"> Infineon Technologies AG, Regensburg, Germany 	<ul style="list-style-type: none"> Infineon Technologies (Kulim) Sdn. Bhd, Kulim, Malaysia
Wafer test	<ul style="list-style-type: none"> Infineon Technologies AG, Villach, Austria 	<ul style="list-style-type: none"> Infineon Technologies (Kulim) Sdn. Bhd, Kulim, Malaysia
Assembly location	<ul style="list-style-type: none"> PT Unisem Batam Island, Indonesia 	<ul style="list-style-type: none"> Amkor Philippines
Bill of Material (BoM)	<ul style="list-style-type: none"> Infineon robust-green BoM 	<ul style="list-style-type: none"> Amkor automotive green standard BoM (including Cu wirebond)
MSL	<ul style="list-style-type: none"> 3 	<ul style="list-style-type: none"> 2a

► **Product Identification:**

- New SP/OPN number
- On Product Level: New location marking „K3A“ behind datecode.

► **Impact of Change:**

There is no change in form, fit, function and electrical performance. Quality and reliability verified by qualification. The device dimensions will remain unchanged.
We are able to improve MSL capability from MSL3 to MSL2a.
The final test location will remain unchanged at Infineon.

► **Attachments:**

N.A.

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► Time Schedule:

■ Final qualification report:	Available
■ First samples available:	Available
■ Intended start of delivery:	01-July-2017 or earlier after customer release

Refer to page x/xx:

■ Last order date of unchanged product:	31-July-2017
■ Last delivery date of unchanged product:	31-Januar-2018

If you have any questions, please do not hesitate to contact your local Sales office.

PRODUCT REPLACEMENT



referring to PCN N° 2016-069-A

■ Last order date of unchanged product:	2017-07-31
■ Last delivery date of unchanged product:	2018-01-31

CURRENT				NEW (REPLACEMENT)			
Device	Ordering Code	OPN	Package	Device	Ordering Code	OPN	Package
TLE7269G	SP000104277	TLE7269GXUMA1	PG-DSO-14	TLE7269G	SP001361106	TLE7269GXUMA3	PG-DSO-14